L	Hits	Search Text	DB	Time stamp
Number				
7	45464	,	USPAT;	2004/03/19
		dielectric)	US-PGPUB;	17:29
			EPO; JPO;	
			DERWENT;	
_			IBM_TDB	
8	4443653	via hole plug stud	USPAT;	2004/03/19
			US-PGPUB;	17:30
			EPO; JPO;	
			DERWENT;	
_		,	IBM_TDB	0004/02/10
9	490420	pad	USPAT;	2004/03/19
	j		US-PGPUB;	17:30
		•	EPO; JPO;	
			DERWENT;	
4.5			IBM_TDB	0004/00/10
10	5025		USPAT;	2004/03/19
		(insulat\$3 dielectric)) and (via hole	US-PGPUB;	17:31
	1	plug stud) and pad	EPO; JPO;	
			DERWENT;	
11	15422		IBM_TDB	2004/03/10
11	15433	bump near2 (electrode conduct\$3)	USPAT;	2004/03/19
			US-PGPUB;	17:32
			EPO; JPO;	
			DERWENT;	
12	224	///interlayer inter-layer) near?	USPAT;	2004/03/19
12	234	(((interlayer inter-layer) near2 (insulat\$3 dielectric)) and (via hole	US-PGPUB;	17:32
		plug stud) and pad) and (bump near2	EPO; JPO;	11.52
		(electrode conduct\$3))	DERWENT;	
		(elections conducts))	IBM TDB	
	1		T DM T DD	<u> </u>